Displaytech a seacomp company

TFT LCD Module Product Specification

162GCOG BA BC 16x2 Characters COG

September 2, 2019

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Revision Record

REV	CHANGES	DATE
00	First release	Sep 2, 2019

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1. FEATURES

The features of LCD are as follows

- * Display mode : STN (Y-G) /Reflective / Positive
- * Display Format : Character
- * IC : ST7032I
- * Interface Input Data : 6800-8bit interface
- * Driving Method : 1/16 DUTY , 1/5 BIAS
- * Viewing Direction : 6 O'clock

2. MECHANICAL SPECIFICATIONS

Item	Specification	Unit
Dimensional Outline	65.0(L)x27.7(W)x2.7 (H)	mm
LCD SIZE	65(L) x19.7/ 27.7(W) x2.1MAX(H)	mm
Viewing Area	61.0(L) x15.7(W)	mm
Character Font	Character number	-

3. ELECTRICAL SPECIFICATIONS

3-1. Absolute Maximum Ratings

(Vss=0V)

ltem	Symbol	St	Unit			
		Min.	Туре.	Max.		
Power Supply Voltage	V _{DD}	-0.3	-	+6.0	V	
LCD Drive Voltage	D _{LCD}	7.0-V _{SS}	-	-0.3+V _{SS}	V	
Input Voltage	V _{IN}	-0.3	-	VDD+0.3		
Operating Temp.	T _{OP}	0	-	+50	°C	
Storage Temp.	T _{ST}	-10	-	+60	°C	
Weight	-	-	9.75	-	g/pcs	

Note 1) Vdd based on VSS=0V

3-2. Electrical Characteristics

(Vss=0V)

Item		Symbol	Test condition	Min.	Тур.	Max.	Unit
Logic Sup	ply Voltage	V _{DD} -V _{SS}	V _{DD} -V _{SS} Ta=-25℃		5.0	5.3	V
LCD Drive Voltage (Recommended Voltage)		V _{OP} =V _O -V _{SS}	Ta=25 ℃	4.3	4.5	4.7	V
Input	"H"Level	VIH	Ta=25℃	0.7VDD			V
Voltage	"L"Level	VIL		0		0.2VDD	V
Output	"H"Level	V _{OH}	I _{OH} =-1.0mA	0.75VDD			V
Voltage	"L"Level	V _{OL}	I _{OL} =1.0mA			0.8	V
Current Consumption		I _{DD}	V _{IN} =VDD or VSS	-	0.23		mA

NOTE: 1) Duty Ratio=1/16, Bias Ratio=1/5

2).Measuring in Dots ON-state

4. POWER SUPPLY

5. ELECTRO – OPTICAL CHARACTERISTICS FOR LCD

ltem	Symbol	Temp	Min	Туре	Max	Unit	Conditions	Note													
Driving Voltage	V _{OP}	25 ℃	4.3	4.5	4.7	V	-	-													
Viewina	θ(Φ=0°)		-	35	-																
Angle	θ(Φ=180°)	25℃	-	35	-	Degree		Note1													
(Cr≧2)	θ(Φ=90°)	200	-	30	-	Degree	Degree	Degree	Degree	Degree	Degree	Degree	Degree	Degree	Degree	Degree	Degree	Degree	Degree	_	Note2
	θ(Φ=270°)		-	45	-																
Contrast Ratio	Cr	25 ℃	-	3	6	-	-	Note3													
Deenenee		0°C	-	400	800																
Response Time(rise)	Tr	25℃	-	80	160	ms	-														
		50℃	-	60	120			Note4													
Deenenee		0°C	-	450	900			NOICH													
Response Time(fall)	Tf	25℃	-	100	200	ms	-														
		50 ℃	-	60	120																

Note1 . Definition of Angle $\Theta \& \Phi$	Note2. Definition of Viewing Angle O1&O2
A B B B B B B B B B B B B B B B B B B B	(a) Show (a)
Note3 . Definition of Contrast Ratio	Note4. Definition of Response Time
Silon Selected dots 50% Whi Vth2 Operation voltage(vop) Vop	Non-Selected Woveforn - Non-Selected Woveforn

6. TERMINAL FUNCTIONS

Pin	Symbol	Function Description						
1	RES	External reset pin.						
2	RS	Select registers.						
3	CS	Chip selection input with pull-high resistor						
4	RW	Select read or write.						
5	E	Starts data read/write.						
6	D0							
7	D1	Four low order bi-directional data bus pips						
8	D2							
9	D3							
10	D4							
11	D5	Four high order bi-directional data bus nins						
12	D6							
13	D7							
14	VSS	Ground						
15	VDD	Power supply input.						
16	VOUT	LCD driver supply voltages.						

7. AC CHARACTERISTICS

Timing Characteristics

68 Interface



							(Ta	a = 25°C)
ltem	Signal	Symbol	Condition	VDD=2.7 to 4.5V Rating		VDD=4. Rat	Units	
	olgilai	Cymbol	Condition	Min.	in. Max. Min. Ma		Max.	onits
Address hold time	RS	tанө		20	-	20	-	ns
Address setup time	RS	taw6		20	-	20	-	
System cycle time	RS	tcyc6	—	400	-	280	-	ns
Data setup time	D0 to D7	tDS6		100	-	80	-	ne
Data hold time	D0 to D7	tdh6		40	-	20	-	115
Access time	D0 to D7	tacc6	C = 100 pE	-	500	-	400	
Output disable time	D0 to D7	tон6		300	-	150	-	ns
Enable Rise/Fall time	E	tr,tf	_	-	20	-	20	ns
Enable H pulse time	E	tewн	_	200	-	120	-	ns
Enable L pulse time	E	tewl	_	150	-	130	-	ns

Note: All timing is specified using 20% and 80% of VDD as the reference.

8. INSTRUCTION SET

Instruction Table:

ST7032-0D (ITO option OPR1=1, OPR2=1)

67-64 63-60	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000																
0001																
0010																
0011																
0100																
0101																
0110																
0111																
1000																
1001																
1010																
1011																
1100																
1101																
1110																
1111																

9. QUALITY SPECIFICATIONS

9 -1. LCM Appearance and Electric inspection Condition

1. Inspection will be done by placing LCM 30cm away from inspector's eyeballs under normal illumination.



2. View Angle: with in 45° around perpendicular line.

9 - 2. Definition

1、COB



2、Heat Seal



 $3\sqrt{TAB}$ and COG



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9-3. Acceptance

Major defect:	AQL = 0.65
Minor defect:	AQL = 1.5

9-4. Criteria

1.COB

Defect	Inspection Item	Inspection Standards	
Major	PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm ²	Reject
Major	Height of coating epoxy	Exceed the dimension of drawing	Reject
Major	Void or hole of coating epoxy	Expose bonding wire or IC	Reject
Major	PCB cutting defect	Exceed the dimension of drawing	Reject

2.SMT

Defect	Inspection Item	Inspection Stan	dards
Minor	Component marking not readable		Reject
Minor	Component height	Exceed the dimension Of drawing	Reject
Major	Component solder defect (missing , extra, wrong component or wrong orientation		Reject
Minor	Component position shift component soldering pad \downarrow \downarrow \downarrow \downarrow \downarrow \downarrow \downarrow \downarrow	X < 3/4Z Y > 1/3D	Reject Reject
Minor	Component tilt component D Soldering pad	Y > 1/3D	Reject

3. Metal (Plastic) Frame

Defect	Inspection Item	Inspection Standards				
Major	Crack/breakage	Anywhere		Reject		
		\\\/		1	Acceptable of	
		vv		L	Scratch	
		W<0.1mm	I	Any	Ignore	
		0.1≤W<0.2mm	L≪	5.0mm	2	
Minor	Frame Scratch	0.2≤W<0.3mm	L≪	3.0mm	1	
		W≥0.3mm	1	Any	0	
		Note : 1. Above criteria appli greater than 5mm. 2. Scratch on the bac ignored .	icable to k side of	scratch line	s with distance visible) can be	
				Ac De	ceptable of nts / Pricks	
	Frame Dent , Prick $\Phi = \frac{L+W}{2}$	Φ<1.0mm		2		
Minor		1.0<Ф<1.5mm		1		
		1.5mm<Φ			0	
		Note : 1. Above criteria appli distance greater tha 2. Dent / prick on the ignored	icable to an 5mm back sid	any two der e of frame (nts / pricks with not visible) can be	
Minor	Frane Deformation	Exceed the	dimensi	on of drawir	ng	
Minor	Metal Frame Oxidation	Any rust				

4. Flexible Film Connector (FFC)

Defect	Inspection Item	Inspection Standard	S
Minor	Tilted soldering	Within the angle +5 ⁰	Acceptable
Minor	Uneven solder joint/bump		Reject
Minor	Hole <u>L+W</u>	Expose the conductive line	Reject
Minor $\Psi = \frac{1}{2}$	Φ > 1.0mm	Reject	
	Position shift	Y > 1/3D	Reject
Minor	Y - V - P - T - T - T	X > 1/2Z	Reject

5. Heat seal /TCP /FPC

Defect	Inspection Item		Inspection Standar	ds
Major	Scratch	expose conductive layer		Reject
Minor	Hole	$\Phi = \frac{L+W}{2}$	Φ> 0.5mm	Reject
Major		Adhesion strength	Less than the specification	Reject
Minor	Minor Position shift		Y > 1/3D	Reject
			X > 1/2Z	Reject
Major	C	onductive line break		Reject

6. Backlight backing protective Film and Others

Defect	Inspection Item	Inspection Standards	
		Acceptable number of units	
		Φ<0.25mm	Ignore
	or Backlight dirty,prick	0.25mm<Φ<0.35mm	2
Minor		0.35mm<Φ<0.45mm	1
		Φ>0.45mm	0
		The distance between any two spots should be Any spot/dot/void outside of viewing area is acce	>5mm eptable
Minor	Protective film tilt	Not fully cover LCD	Reject

7. Electric Inspection

Defect	Inspection Item	Inspection Standards	
Major	Short		Reject
Major	Open		Reject

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8. Inspection Specification of LCD

DEFECT	ITEM	CRITERIA
1 Crack (minor)		 X>1/8 length of the long side REJ Y:damaged, 1/3 of the adhesive exposed REJ Ignoring Z
2 Segment Deformation (major)	B	 Ignoring the length B>1/3 width of conductor REJ
3 Segment Deformation (major)		Referring to the project-drawing
4 Segment Deformation (major)	$\begin{array}{c} z \\ \downarrow \\ \downarrow \\ \uparrow \\ \downarrow \\ \downarrow \\ \downarrow \\ \downarrow \\ \downarrow \\ \downarrow \\ \downarrow$	 Z<t,x、y 1="" 2="" main<br="" not="" of="" reaching="" width="">seal or conductive point .</t,x、y> REJ 2.A>1/3D.
5 Crack (minor)	X Z Y	1. X>1/8 length of the long-side REJ 2.Y1/3 of the Adhesive exposed REJ
6 Crack (minor)	T T T T T T T	1. At the side of conductor $Z \le 1/2T$ ACC2. At the side of non- conductor $Z \le 1/2T$ X>5mmREJY \ge 1/3DREJZ>1/2TZ > 1/2TREJ

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7	D W W	1.X≤2mm and Y≤1.5mm AC		ACC	
Crack	Crack (minor)		Y<1/2D		
(minor)			nd Y≤3/4D, I	gnoring Z	ACC
8 Crack (major)					REJ
9	Dirty spots	POSITIVE	MODE	ACC QTY	
Dirty spots	Round type	$0 \text{ mm} < \emptyset \le 0$	J.3mm i≤0.4mm		
Round	Ø=(L+W)/2	0.4mm<Ø	i≤0.5mm	2	
type		0.5mm< Ø	j	0	
(minor)					
10	Polarizer deviated from the	1.Protruding the edge of glass beyond			
	glass	U.2mm (Total dimension of alass must be within)		n)	
minor		(Total dimension of glass must be within)			n) ce
					REJ
		2. Distance inside the edge of glass is beyond		eyond	
		1.4mm REJ		REJ	
		If project-d	lrawing has o	other specification	ons
		refer to ther	n		
11		DIME	NSION		
/ · · · ·	Linear type		WIDTH	ACC QIY	
(minor)	Polarizer scratch		≤0.08mm	Ignore	
	(OT VISIDIE STATE)	≤4mm	≤0.10mm	2	
		≤3mm	≤0.12mm	2	
		W>0.	12mm	0	
		Ignoring it, i	f beyond vie	w area	

12	Ø=(L+W)/2	POSITIVE MODE	ACC QTY
(minor)	Air bubble between glass and	Ø≤0.3mm	Ignore
	polarizer, polarizer with folding	0.3mm< Ø≤0.4mm	4
	trace(of visible state)	0.4mm< Ø≤0.5mm	2
	Ø=(L+W)/2	0.5mm<Ø	0
		Ignoring it, if beyond vie	ew area

13 (minor)	Polarizer pricked and damaged(spots) (of visible state) Ø=(L+W)/2	Positive mode $\Phi \leq 0.8 \text{mm}$ $0.8 < \Phi \leq 1.0 \text{mm}$ $\emptyset > 1.0 \text{mm}$ Ignoring it, if beyond	Acc qty 2 1 0 nd view area	
14 (minor)	Conductor dirty	With oil-stain or fo	reign substan	ce REJ
15 (minor)	Polarizer without protected film			REJ
16	The width of the Adhesive	≤1/2 of the averag	e width	REJ
(minor)		≥3/2 of the averag	e width	REJ
17 (minor)	The Adhesive deviation	Beyond view area		REJ
18 (major)	The Adhesive impure	≥of the width of ac (Air bubble in the Adhesive REJ)	lhesive adhesive= of	REJ the width of the
19 (major)	The Adhesive Varicolored			REJ
20 (minor)	Seal resin discolored or off the edge of the glass			REJ
21 (minor)	The height, width and deviation quantity of seal resin	Beyond project-dra	awing permiss	sible tolerance REJ
22	Permeating resin	Beyond view area		REJ
(minor)	(Permeating quantity of seal resin)	(If customers have additionally.)	e special requi	rements, make
23 (major)	Length and type of a pin	Referring the proje	ect-drawing	

24 (minor)	Pin leaning	If project-drawing has specifications, refer to them
25	Pin with resin except its head	
(minor)	(including pin-let)	REJ
26 (minor)	Pin-resin uncured	REJ
27 (minor)	Polarizer dirty or space between Polarizer and glass with pin-resin	REJ

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28 (minor)	Pin-resin's height excess the	If project-drawing has specifications, refer to						
29	Pin resin broken	REJ						
(minor)								
30	Carbureted-adhesive exposed	Excess 1/2 of the interval of conductor						
(minor)				REJ				
		(If customers have special requirements, make						
		additionally.)	1	-				
31	Pin hole, vacancy		ACC QTY	_				
		0mm< Ø≤0.3mm	Ignore					
(minor)		0.3mm< Ø≤0.4mm	4					
		0.4mm< Ø≤0.5mm	2					
	/ vacancy	0.5mm< Ø	0					
	Pin hole							
	Ø=(L+W)/2							
32	Inclined combination	1.B—A>0.25mm	R	EJ				
(minor)		2.A/B≤3/4	REJ					
		3.Extra line made by inclined combination must						
		be checked before acceptance according to the						
		criteria of item 11"linear type"						
	Ø=(L+W)/2	4. Choose one freely between 1 and 2						
		will be checked befor	e by inclined combined combined according to the second second second second second second second second second	ding to				
		the criteria of item 38		ang to				
		6.Character deformed will be checked before						
		acceptable according to the limitation of the sample						

33 (minor)	Point matrix, Pin hole, vacancy	0mm< Ø≤0.3mm 0.3mm< Ø≤0.4mm 0.4mm< Ø≤0.5mm 0.5mm< Ø	ACC QTY Ignore 4 2 0
---------------	---------------------------------	--	----------------------------------

34	Protrusion	1. A>1.0mm	REJ
(minor)	$B \rightarrow \downarrow$ $B \rightarrow \downarrow$ $\phi = (L+W)/2$	2.B>0.2mm	REJ
35	Point matrix: Combination of character inclined	1.Quantity deformed A≤±15% 2.Quantity deformed B≤±15%	ACC ACC
(minor)			
36 (minor)	Color variation	Referring to the limitation of the sam	ple
37 (major)	Segment crossing Segment missing		REJ
38 (major)	Conduction of silver-dot out of condition		REJ
39 (major)	Incomplete segment	Referring to the limitation of the sam	ple
40 (major)	Incomplete common		REJ
41 (major)	Excessive segment		REJ
42 (minor)	Reacting slowly	Referring to the limitation of the sam	ple
43 (major)	Strong current	≥2uA/Cm ²	REJ
44 (minor)	Uneven surface	Referring to the criteria of item 9	

10. RELIABILITY

NO.	ltem	Condition	Criterion		
1	High Temperature Operating	50°C,240 Hrs			
2	Low Temperature Operating	0°C, 240Hrs	No defect in cosmetic		
3	High Temperature Storage 60°C, 240Hrs		and operational function allowable.		
4	Low Temperature Storage	-10°C, 240Hrs]		
5	High Humidity	40°C, 90%RH, 240Hrs	Total current		
6	Thermal Shock	-10°C to 25°C to 60°C (30Min) (5Min) (30Min) 10Cycles	be below double of initial value.		

Note: 1) For restrict products, the test conditions listed as above must be revised.

11. HANDLING PRECAUTIONS

(1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizers which easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling the LCD Modules.

(2) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommended below) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Trichlorotrifluoroethane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface. Do not use the following solvent:

- Water
- Acetone
- Aromatics
- (3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before power is turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

(4) Packaging

- Modules use LCD elements, and must be treated as such. Avoid intense shock and falls from a height.
- To prevent modules from degradation. Do not operate or store them exposed directly to sunshine or high temperature/humidity.
- (5) Caution for operation
 - It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.
 - Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's. Which will come back in the specified operating temperature range.
 - If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
 - A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the relative condition of 40°C, 50%RH or less is required.

(6) Storage

In the case of storing for a long period of time (for instance ,for years) for the purpose or replacement use, The following ways are recommended.

- Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light. Keeping temperature in the specified storage temperature range.
- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)
- (7) Safety
 - It is recommendable to crash damaged or unnecessary LCD into pieces and wash off liquid crystal by using solvents such as acetone and ethanol. Which should be burned up later.
 - When any liquid crystal leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

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12. OUTLINEDIMENSION



13. PACKAGE DIMESION

規格要求: 每個外箱內放2個內箱. 一個內箱裝X層產品,共需X個吸塑盤, 每層吸塑之間交錯180度放置,頂部放置1層空吸塑 一個吸塑盤裝X*X=XX個模組, 每層產品底部與頂部各放一層珍珠棉 每個內箱里放X*X*(X-1)=XX個模組. 一個外箱裝模組的數量:X*X*(X-1)*2=XXX 最后,內箱和外箱封口 Part drawing & Spec.revision record during discussion with vendor				1 2 3 4 5 6 7 8	NA 外 内 胶 整 子 MOC PAPER	ME 箱 塑盘 BOARD BOARD	UNIT PCS PCS m PCS PCS PCS PCS PCS PCS PCS	atyper 1 x xx xx xx xx xx xx xx xx x x x x x	spec xxx*xxi xxx*xxi xxx*xxi xxx*xxi xxx*xxi xxx*xxi h Lt	crxxx crxxxx crxxxx crxxx crxxx crxxx crxxx crxxx crxxx crxxx crxxx crxxx crxx	MATERIAL PAPER PE PET EPE PAPER PAPER	R - - - - - - - - - - - - -	EMARK 1"TPY SHAPE D 10 ⁶ 10 ¹¹ D 10 ⁶ 10 ¹¹ EFUL IN PUT B"TPY B"TPY SHEET	
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